

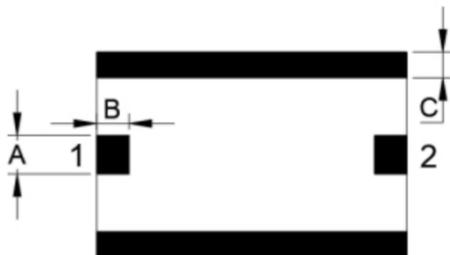
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

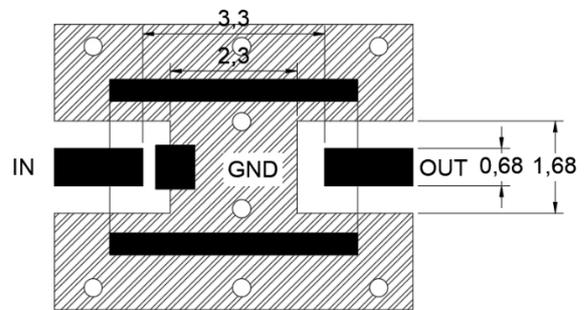
NO.	Parameter	Frequency	SPC		
			MIN	Typ	Max.
1	Insertion Loss (dB)@25°C	800~1250 MHz	-	1.2	1.3
2	VSWR	800~1250 MHz	-	-	2.0
3	Attenuation (dB)	1600~3750MHz	-	40	-
4	Power(W)	2 Max.			
5	In/Output Impedance (Ω)	50			
Operating & Storage Condition (Component)					
Operation Temperature Range: -55°C ~ +85°C					
Storage Temperature Range: -55°C ~ +85°C					
Storage Condition before Soldering (Included packaging material)					
Storage Temperature Range: +5 ~ +40 °C					
Humidity: 30 to 70% relative humidity					

Construction

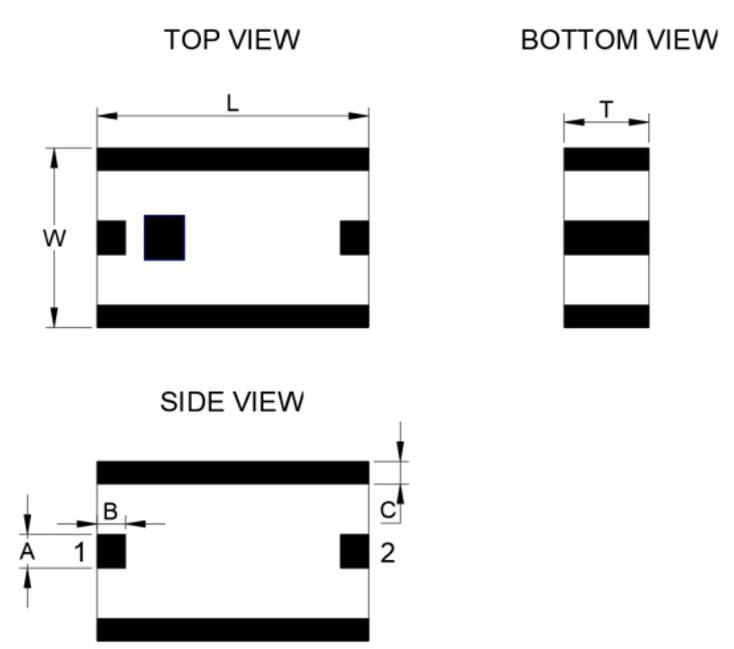


PIN	Connection	PIN	Connection
1	input Port	2	output Port

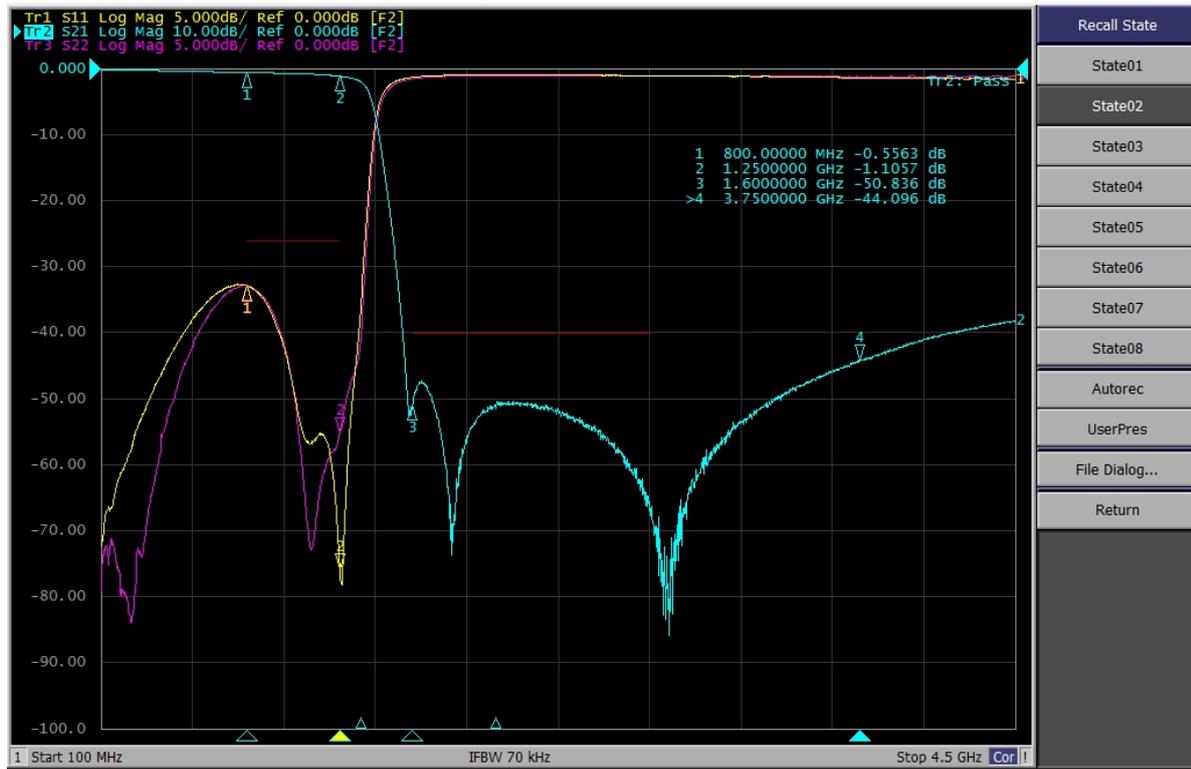
Mounting Considerations



Dimensions

Figure	Symbol	Dimension (mm)
	L	4.50 ± 0.20
	W	3.20 ± 0.20
	T	2.00 MAX
	A	0.60 ± 0.10
	B	0.50 ± 0.10
	C	0.40 ± 0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning

